



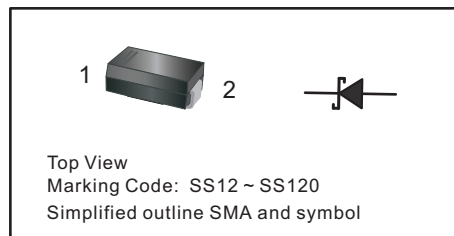
Surface Mount Schottky Barrier Rectifier

Reverse Voltage - 20 to 200 V

Forward Current - 1.0A

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Features

- Metal silicon junction, majority carrier conduction
- For surface mounted applications
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

MECHANICAL DATA

- Case: SMA
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 70mg / 0.0025oz

Absolute Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

Parameter	Symbols	SS12	SS14	SS16	SS18	SS110	SS112	SS115	SS120	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	20	40	60	80	100	120	150	200	V
Maximum RMS voltage	V_{RMS}	14	28	42	56	70	84	105	140	V
Maximum DC Blocking Voltage	V_{DC}	20	40	60	80	100	120	150	200	V
Maximum Average Forward Rectified Current at $T_c = 100\text{ }^\circ\text{C}$	$I_{F(AV)}$	1.0								A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	25								A
Max Instantaneous Forward Voltage at 1 A	V_F	0.55		0.70		0.85		0.90		V
Maximum DC Reverse Current $T_a = 25^\circ\text{C}$ at Rated DC Reverse Voltage $T_a = 100^\circ\text{C}$	I_R	0.3 10			0.2 5			0.1 2		mA
Typical Junction Capacitance ⁽¹⁾	C_j	110			80					pF
Typical Thermal Resistance ⁽²⁾	$R_{\theta JA}$	90								$^\circ\text{C/W}$
Operating Junction Temperature Range	T_j	-55 ~ +150								$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-55 ~ +150								$^\circ\text{C}$

(1) Measured at 1MHz and applied reverse voltage of 4 V D.C.

(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.



Fig.1 Forward Current Derating Curve

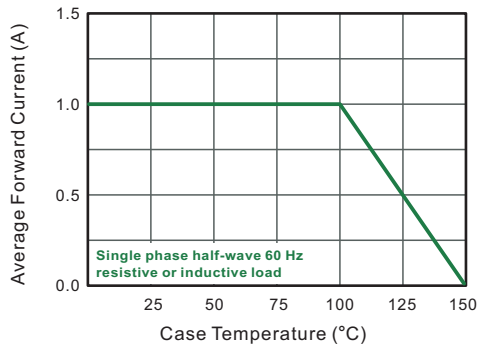


Fig.2 Typical Reverse Characteristics

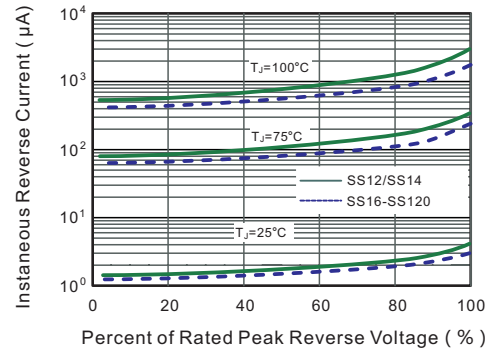


Fig.3 Typical Forward Characteristic

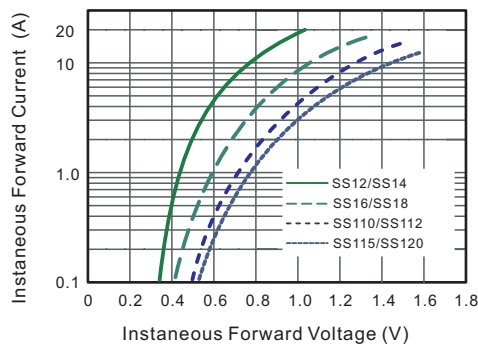


Fig.4 Typical Junction Capacitance

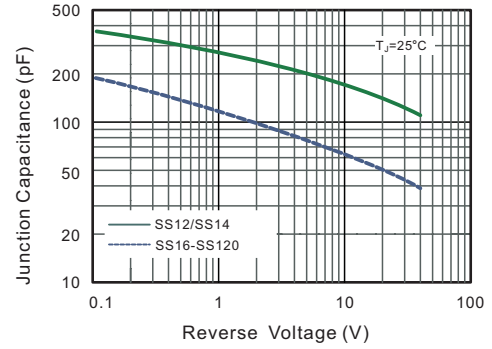


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

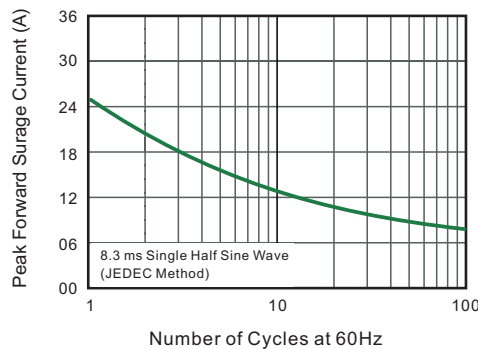
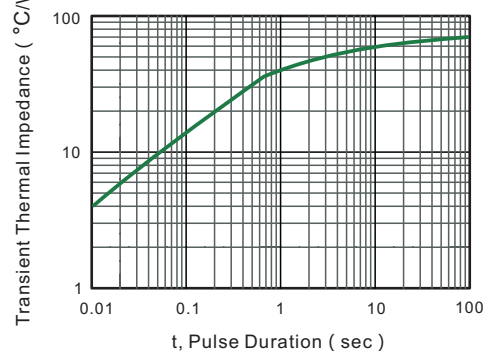


Fig.6- Typical Transient Thermal Impedance

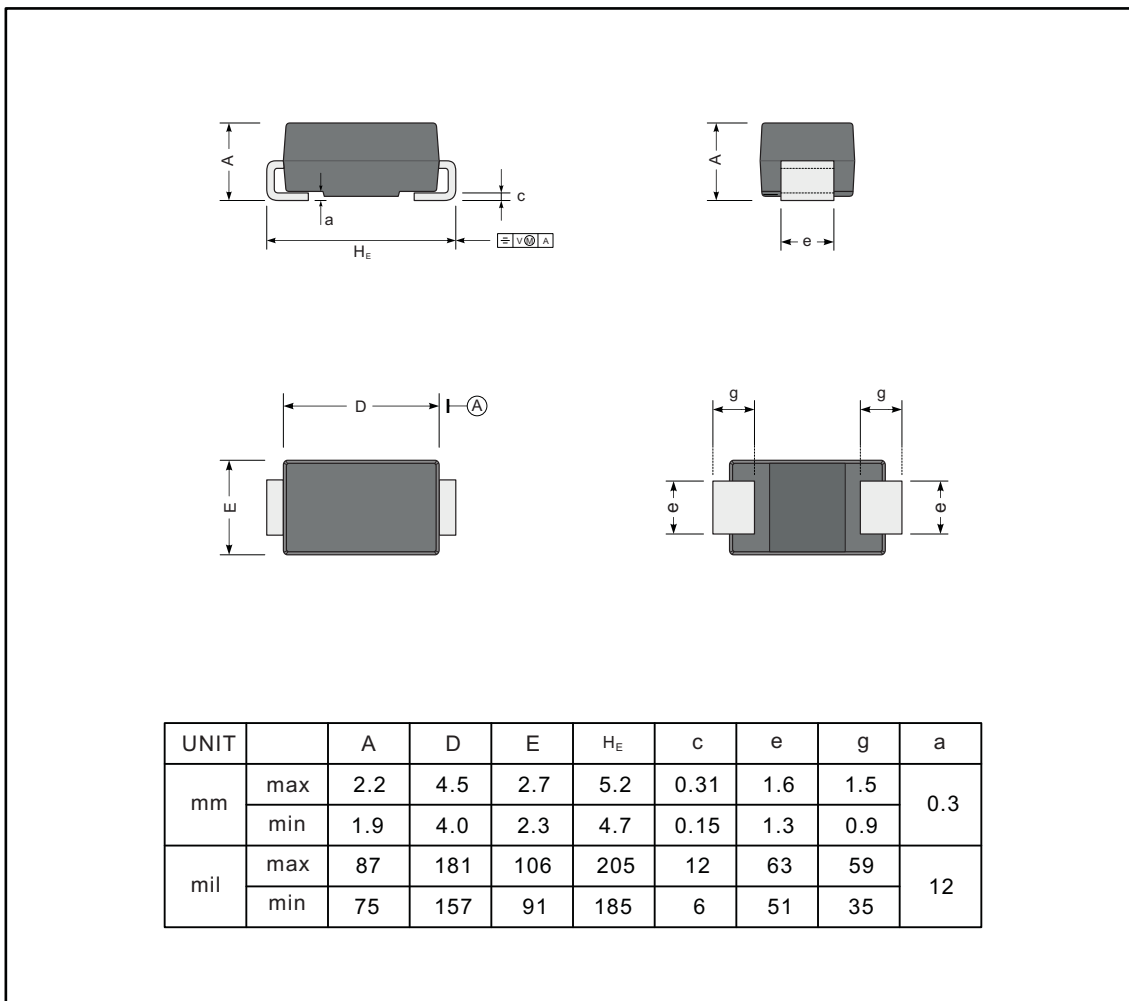




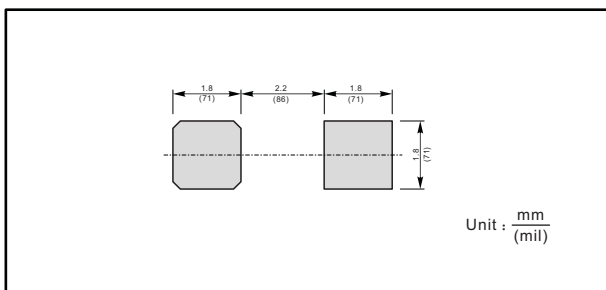
PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SMA



The recommended mounting pad size



Marking

Type number	Marking code
SS12	SS12
SS14	SS14
SS16	SS16
SS18	SS18
SS110	SS110
SS112	SS112
SS115	SS115
SS120	SS120

单击下面可查看定价，库存，交付和生命周期等信息

[>>JINGDAO\(晶导微\)](#)